

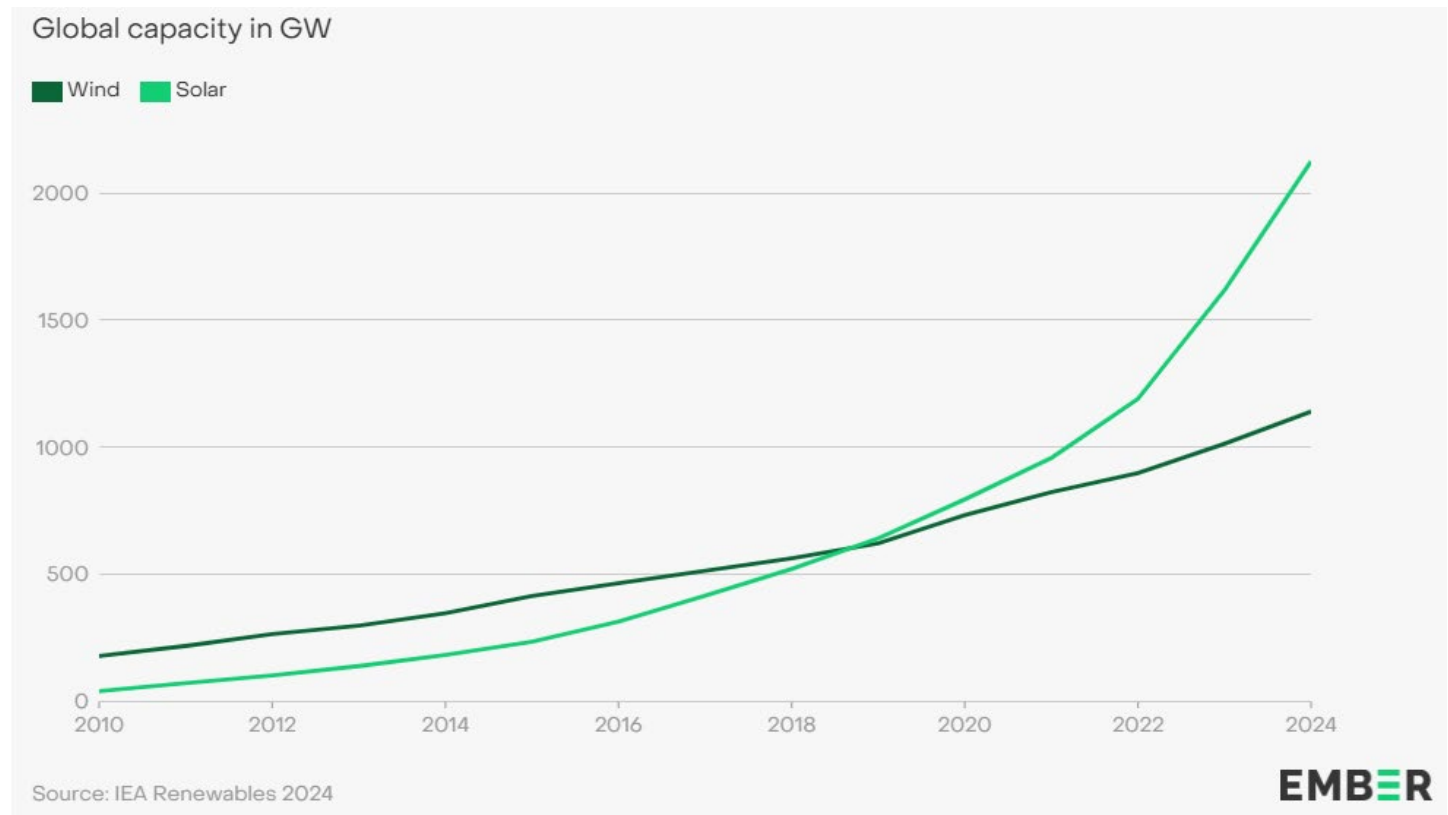
IBC SOLAR CELLS: THE NEXT TECHNOLOGY NODE

David Smith Dec 4, 2024

maxeon

GROWTH OF PV INDUSTRY

- ❑ Global use of energy = 170,000 TW-hr
- ❑ Current PV share = 7 % of electricity markets
- ❑ For 2000 kWhr/kW typical capacity factor, 85 TW is need to power the planet.
- ❑ Assume 25 year product replacement cycles
- ❑ Sustainable annual PV market in the 2-4 TW range.



- ❑ ***There is time for one more PV technology leap prior to steady state market.***
- ❑ ***Let's make sure it is a good one...***

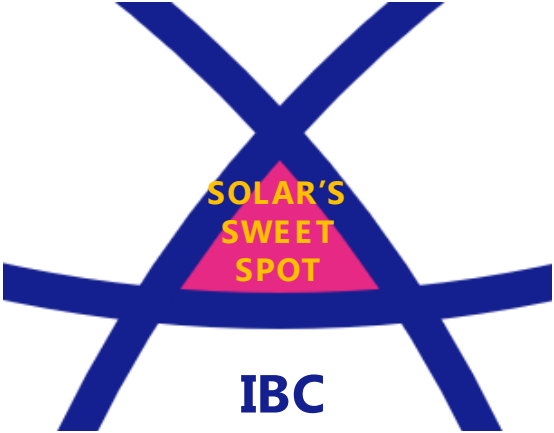
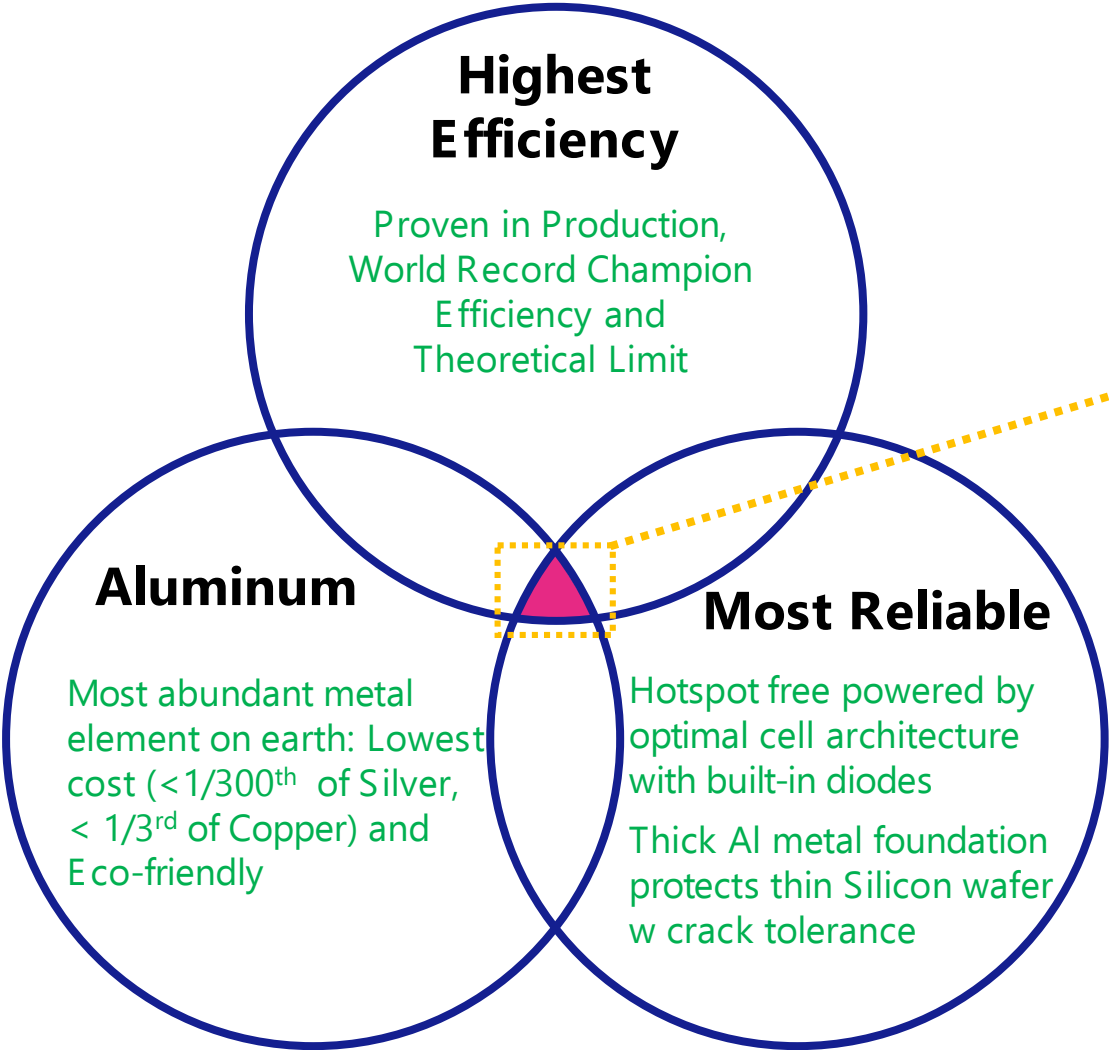
**Founded in 2020
as a spin-off of
SunPower
Corporation,
Maxeon leverages
almost 40 years
of experience.**

Maxeon is a public
company listed on
NASDAQ (MAXN).

COMPANY AT A GLANCE

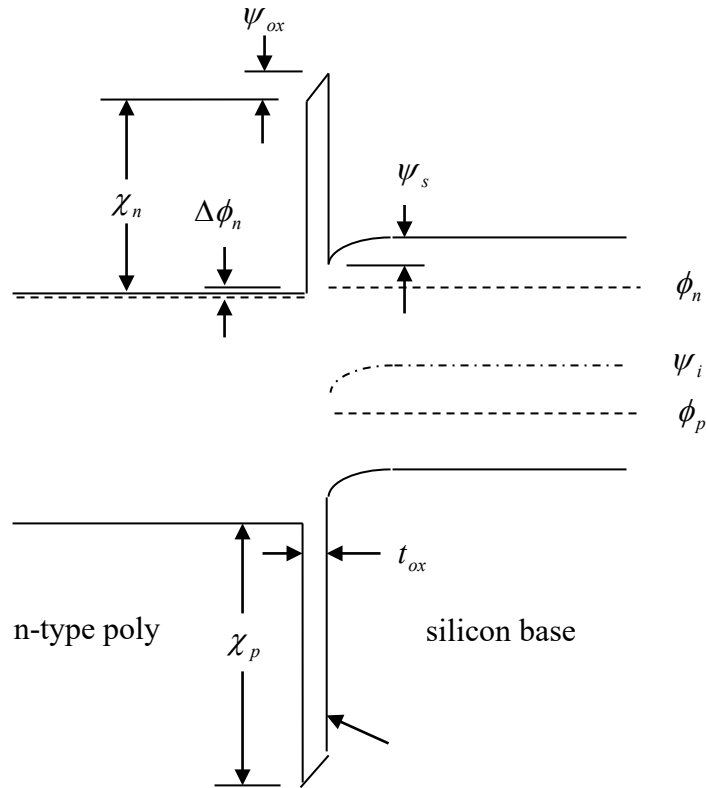
Headquarters	Singapore
2023 revenues	+1,12 B\$
Employees	Approx. 3,900
Experience	Technology leader in the solar industry since 1985
Global reach	100+ Global Markets 1,900+ patents
Customer segments	Residential Commercial Power Plants
Channels to market	~1,700 Sales & Installation Partners
Customer-facing brands	SunPower Brand in most of the world Maxeon Brand in U.S. and Japan markets
2023 volume	+2.8 GW shipments
Number of customers	+1,000,000
Manufacturing capacity	+3.5 GW + JV offtake

IBC: Ultimate Single-Junction Silicon Solar Cell Technology



With a strong ecosystem, IBC will dominate the solar industry in next 3~5 years!

Poly contact



❑ Net result: N poly $J_0 \sim 1 \text{ fA/cm}^2$, P poly $J_0 \sim 6 \text{ fA/cm}^2$ contact or non-contact.

❑ Why does it work so well?

1. Oxide is buried under poly and annealed never to see moisture or oxygen again.
2. Tunnel oxide : Self-limiting growth at polysilicon deposition temperatures.
3. Dopant diffusivity thru SiO_2 is just low enough to severely limit out-diffusion.
4. Out-diffusion is not zero as in Hetero-junction a-Si emitter. Insensitivity to surface prep and defects. For example, particles under-diffused.
5. Metal gettering to Npoly.
6. Damage in poly is irrelevant, buffers post-process issues.

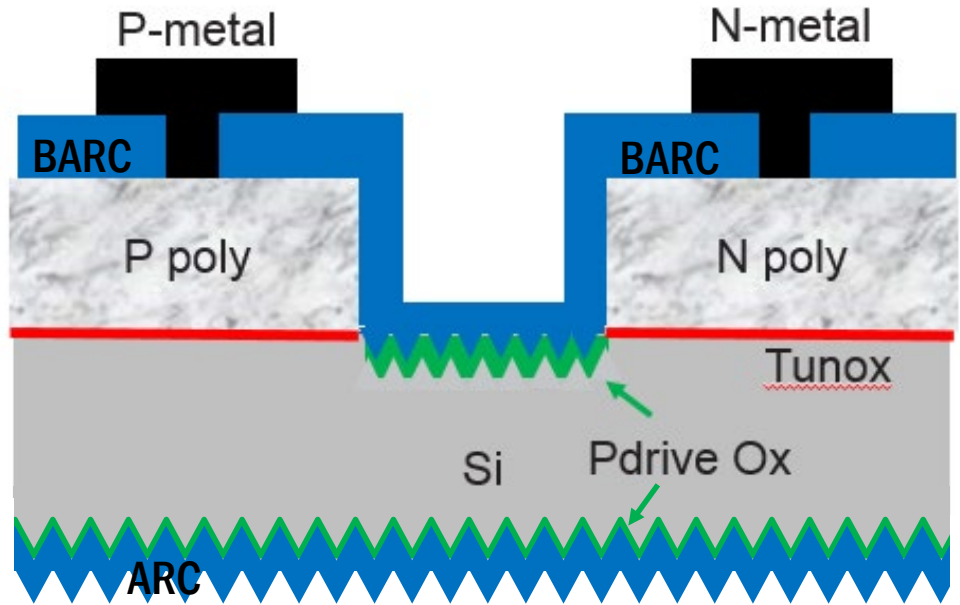
Redundancy. Multiple levels of protection.

Poly emitter band structure for N-type

- ✓ Pile-up of majority carriers at surface
- ✓ Reduction of minority carriers without Auger penalty

IBC IMPLEMENTATION

- ❑ IBC use of polysilicon limited by space charge recombination at butting junction.
- ❑ Multiple solutions, but most robust is trench process.
- ❑ Utilized on Maxeon 3/5/6 products to demonstrate PV industry's first 22 % efficiency modules.
- ❑ *Roadmap: Self-aligned process.*



Maxeon 3 device structure. First demonstrated April 2008.

*Patents: EP 3065184
US 7812250
CN 102057497*

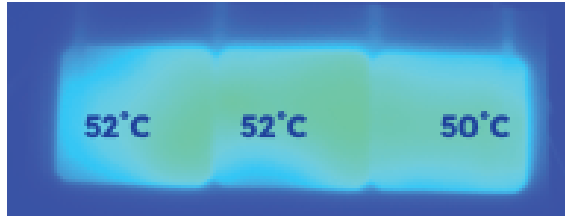
REVERSE BIAS AND SHADING

Conventional cell



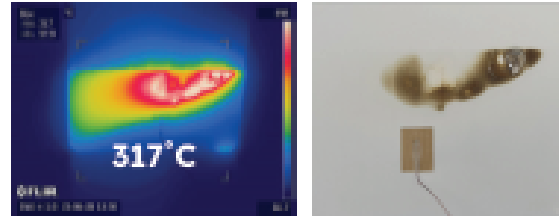
Thermal image of a conventional cell with a defect and failed bypass diode

Maxeon's latest-generation IBC



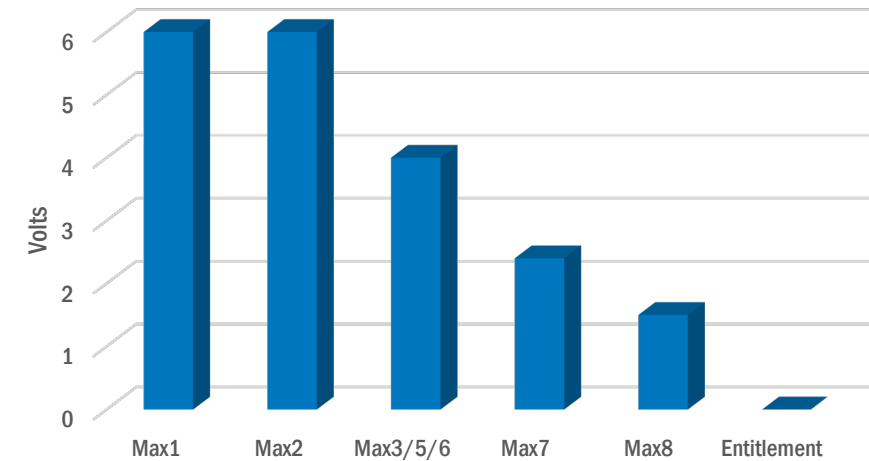
Maximum temperature of Maxeon IBC cells at $-I_{sc}$ in reverse bias with no diodes, 20°C ambient

A competitor's IBC



A competitor IBC module with partial shading of a cell and diodes removed resulted in backsheet burning within 30 minutes

Reverse breakdown at $-I_{sc}$



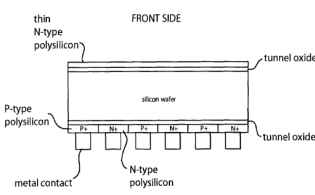
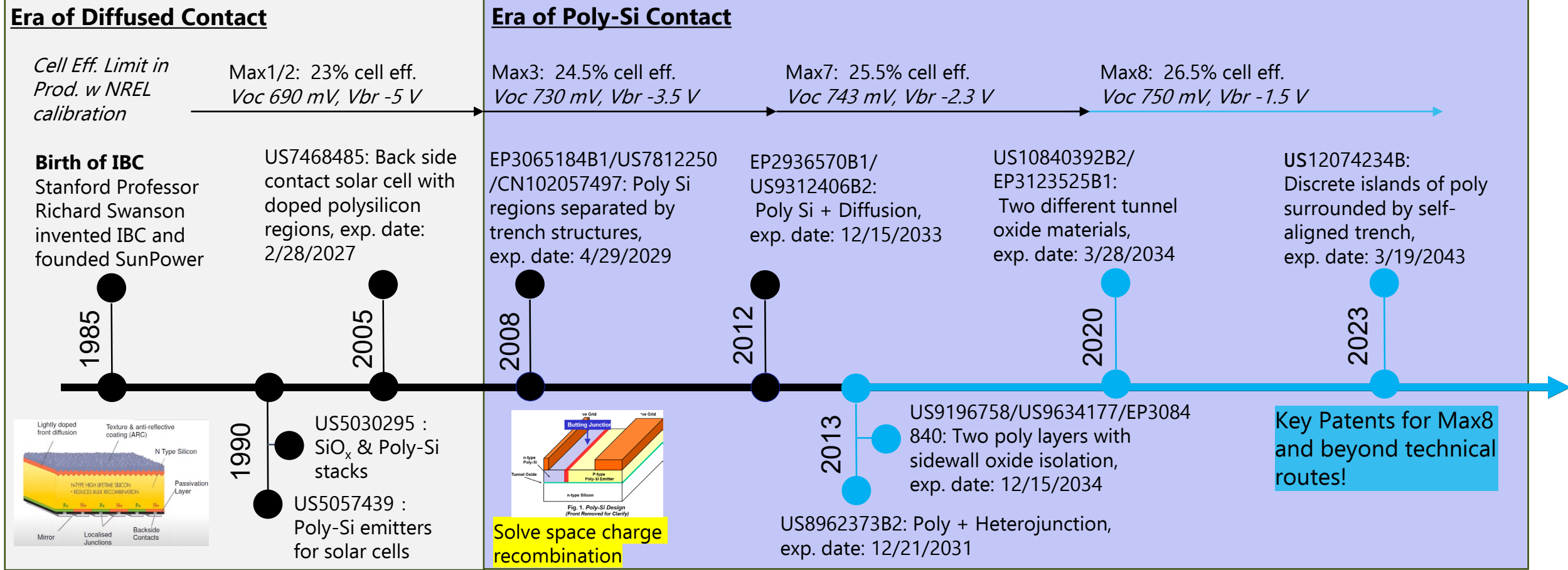
- ❑ Max7 reverse voltage at $-I_{sc}$ is -2.3 volts.
- ❑ Shaded conditions increase cell temperature only 30 C
- ❑ Higher energy yield and fewer reliability issues with local heating.
- ❑ Compare to conventional front contact with very elevated temperatures during diode failure.

What Happened?

- ❑ Generally steady progress thru 2008.
- ❑ Sunpower was efficiency, reliability and cost leader thru this period. Then...

Sunpower	Rest of industry	Consequence
\$40/kg Polysilicon contracts		~ 1 \$B loss
5 inch wafers	M2-M4-M6-G10-G12	High silicon cost, captive supply chain
Specialized inline tools	Large batch	Capex disadvantage, limited growth
High overhead small factories	Local supply chains, China national priority	Persistent high-cost structure
23 % cell in 2008, market introduction 2016	AIBSF → PERC → Topcon	Erosion of efficiency advantage, Time to market delay

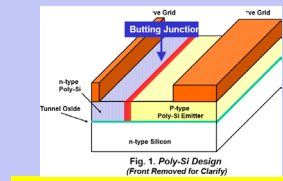
Innovation History of Maxeon IBC Solar Cells



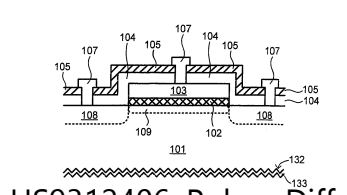
There were many years of Poly-Si contact development, but **fundamental issue was not resolved to enable a high eff. Poly-Si IBC cell**



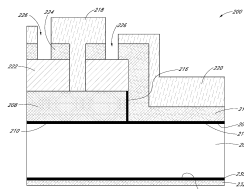
- Achieved 11 World Records in NREL Champion Cell and Module Efficiency Chart
- IBC is the technology beyond TOPCon and is an excellent platform for Tandem



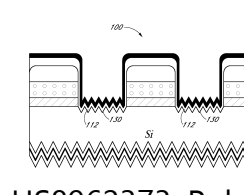
Solve space charge recombination



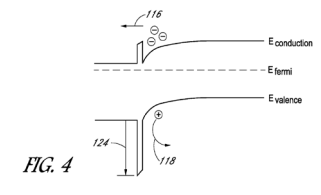
US9312406: Poly + Diff



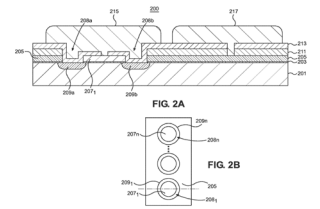
US9196758



US8962373: Poly + HJT



US10840392



US12074234B: Poly Islands

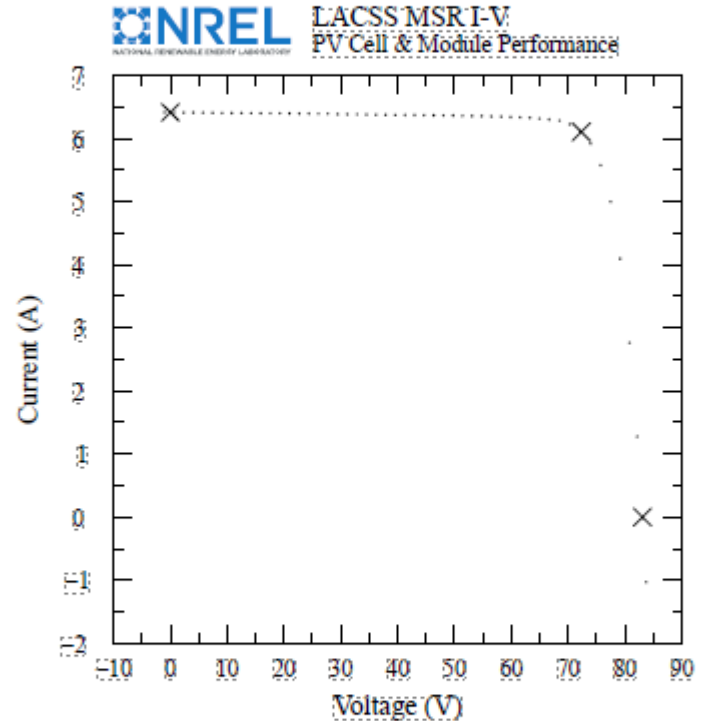
MAXEON 7

- ❑ Max7 product was making 24 % efficiency white backsheet modules in 2023.
- ❑ Champion aperture tested module of 24.9 % in January. 83.08 V/112 cells = 742 mV Voc per cell.
- ❑ Max7 stuck in pilot operation due to factors beyond our control
 1. Inventory overhang due to industry over-capacity
 2. Detention of Maxeon products at US border by CBP
- ❑ Max8 product anticipated to be 25 % efficiency total area, 750 mV per cell.

Maxeon Solar Technologies mono-Si Module

Device ID: YMD231221-2A
Jan 30, 2024 12:47:59 MT
Spectrum: ASTM G173 global

Device Temperature: 25.0 ± 1.5 °C
Device Area = 17753.4 cm² ± 0.20%
Irradiance: 1000.0 W/m²



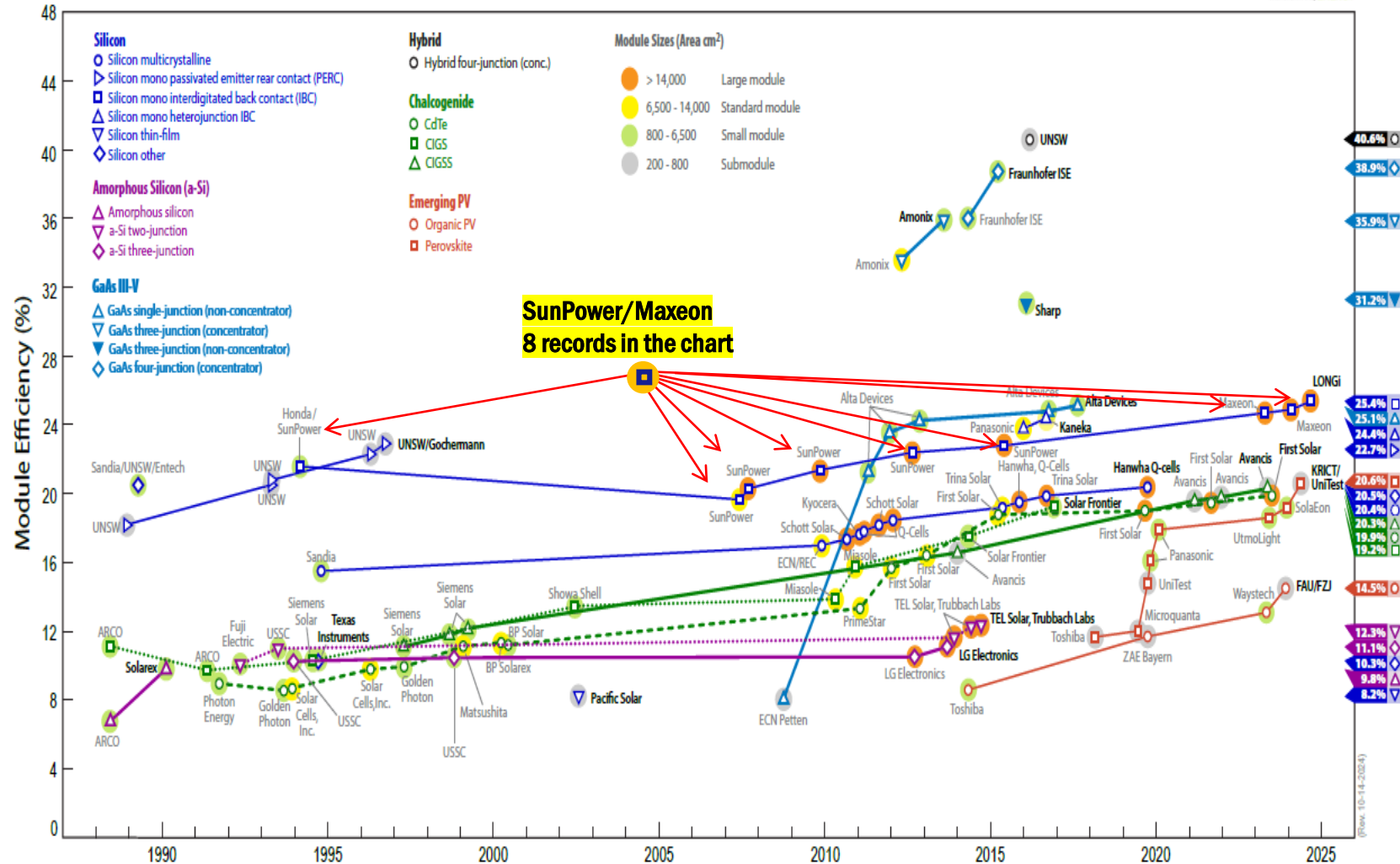
V_{oc} = 83.08 V ± 0.36%
I_{sc} = 6.413 A ± 0.67%
Fill Factor = 82.8% ± 1.38%
Efficiency = 24.9% ± 1.00%

V_{max} = 72.30 V ± 0.36%
I_{max} = 6.103 A ± 0.91%
P_{max} = 441.3 W ± 0.98%

BACK CONTACT INNOVATION LEADERSHIP



Champion Module Efficiencies



<https://www.nrel.gov/pv/assets/pdfs/champion-module-efficiencies.pdf>

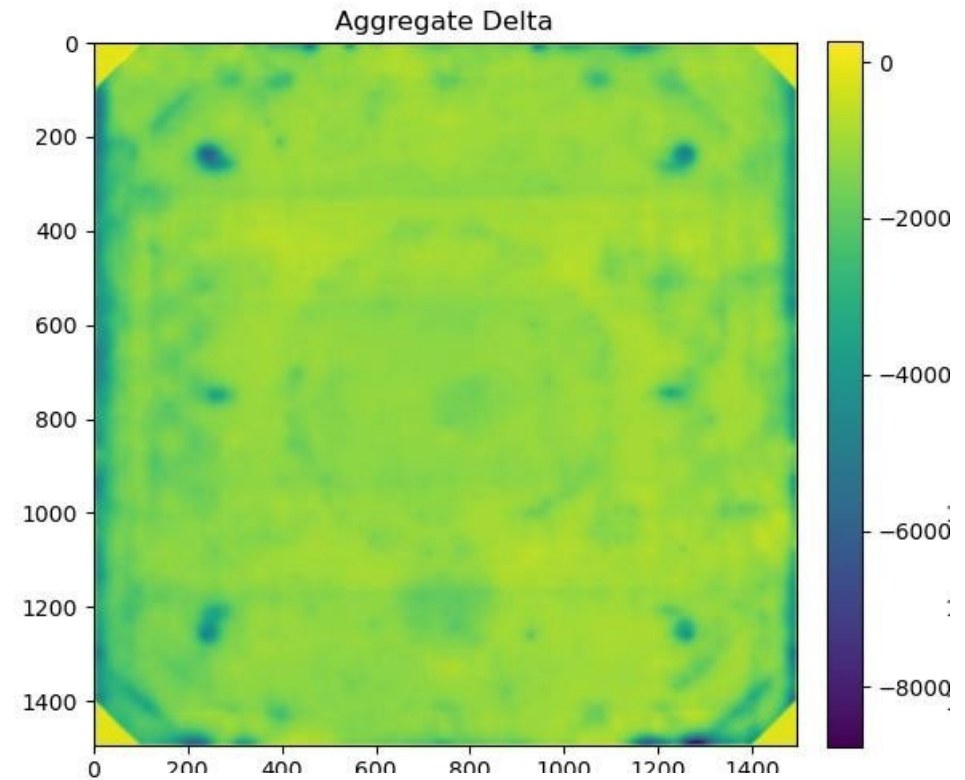
Maxeon IBC: Industry-leading efficiency and reliability. Developed in Silicon Valley, California, USA.

- R&D center in San Jose, CA
- **100+** R&D personnel
- **>1900** patents, most on structures and manufacturing processes for IBC solar cells and modules
- **>20** years experience with high volume IBC manufacturing

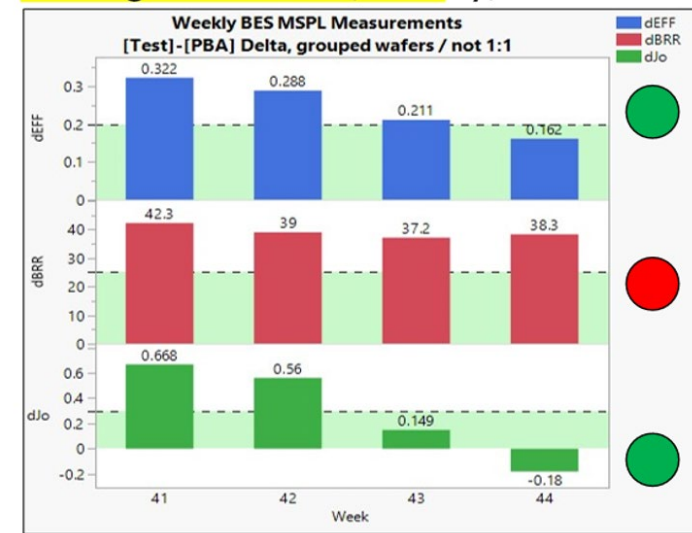


YIELD

- ❑ Maxeon is largely past the era of metal contaminants limiting bulk lifetime.
- ❑ Majority of defects are handling related.
- ❑ Key method: Aggregate PL data to detect recurring defects
- ❑ Frequently found in metallization processes
- ❑ Each process step monitored. Total backend handling losses near 0.2 % efficiency.
- ❑ Many small defects that need continuous focus.



BE Segmentation (Weekly)



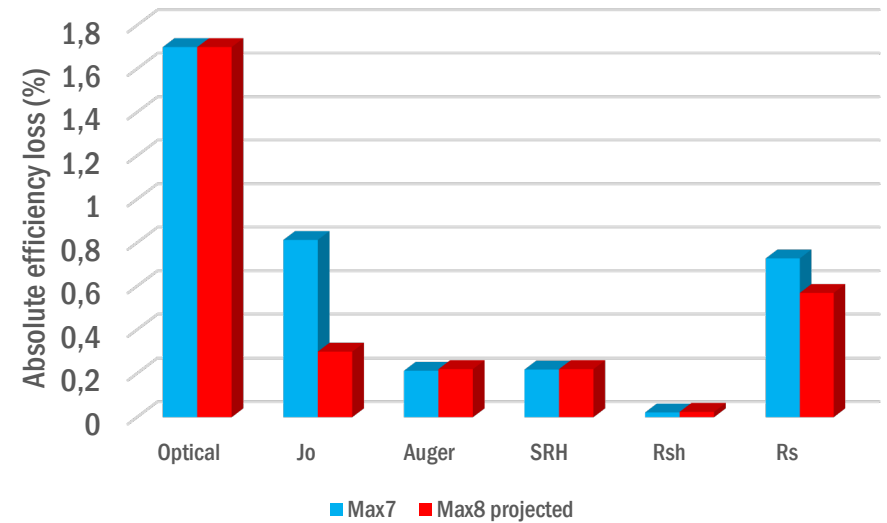
MAXEON 8 IBC

- 25%+ module efficiency
- Low reverse bias
 - Excellent energy yield, passive safety.
- Aluminum Metallization
 - Crack tolerance
 - Lead-free
 - Hail resistant (critical for UPP market)
- 40+ year warranty, lower annual degradation
- Differentiated product in both DG and UPP markets.
- Extensive IBC IP portfolio
- Equivalent manufacturing complexity and structural cost to TopCon.

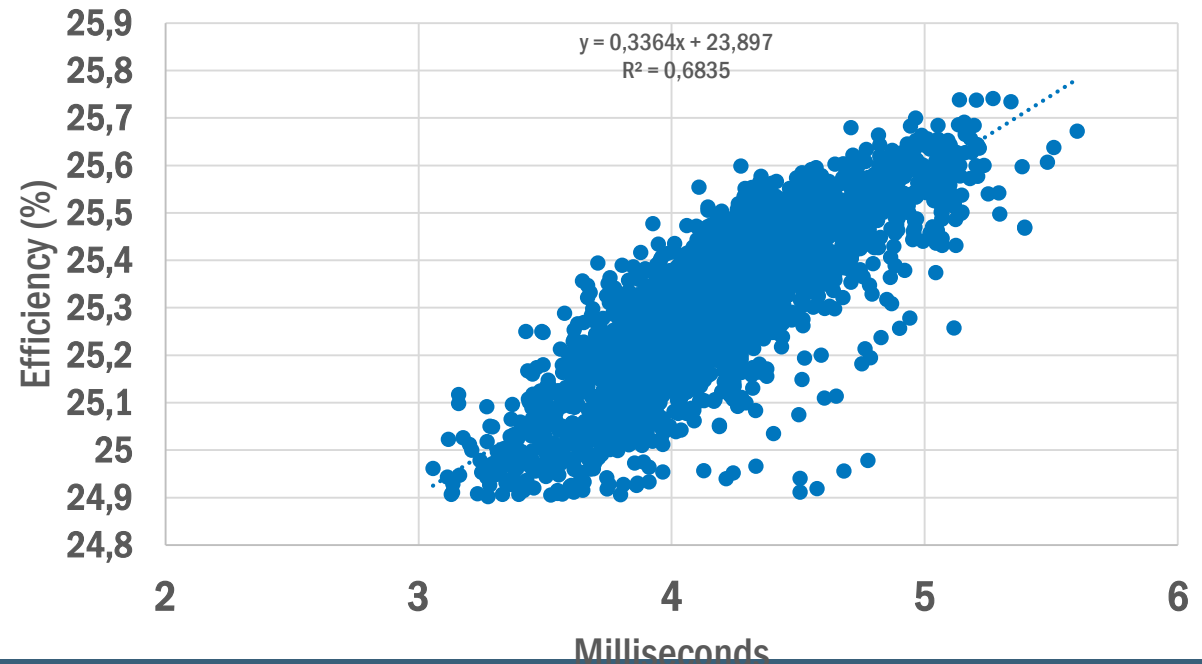


MAXEON 8

- ❑ Currently prototyping on Maxeon 7 process with no step additions. Self aligned micro-trench structure.
- ❑ Efficiency loss analysis for Maxeon 7 and projected for Maxeon 8 at right.
- ❑ Bulk lifetime 20 msec typical no longer significant loss, Jo losses will become small with Max8
- ❑ Anticipate > 26 %
- ❑ Largest remaining loss: poor infrared absorption

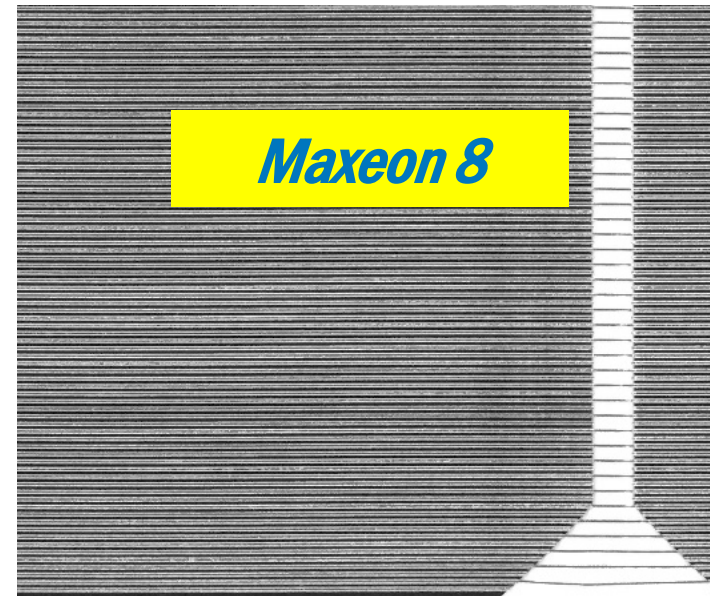


Quantitative PL whole wafer Lifetime (ms)



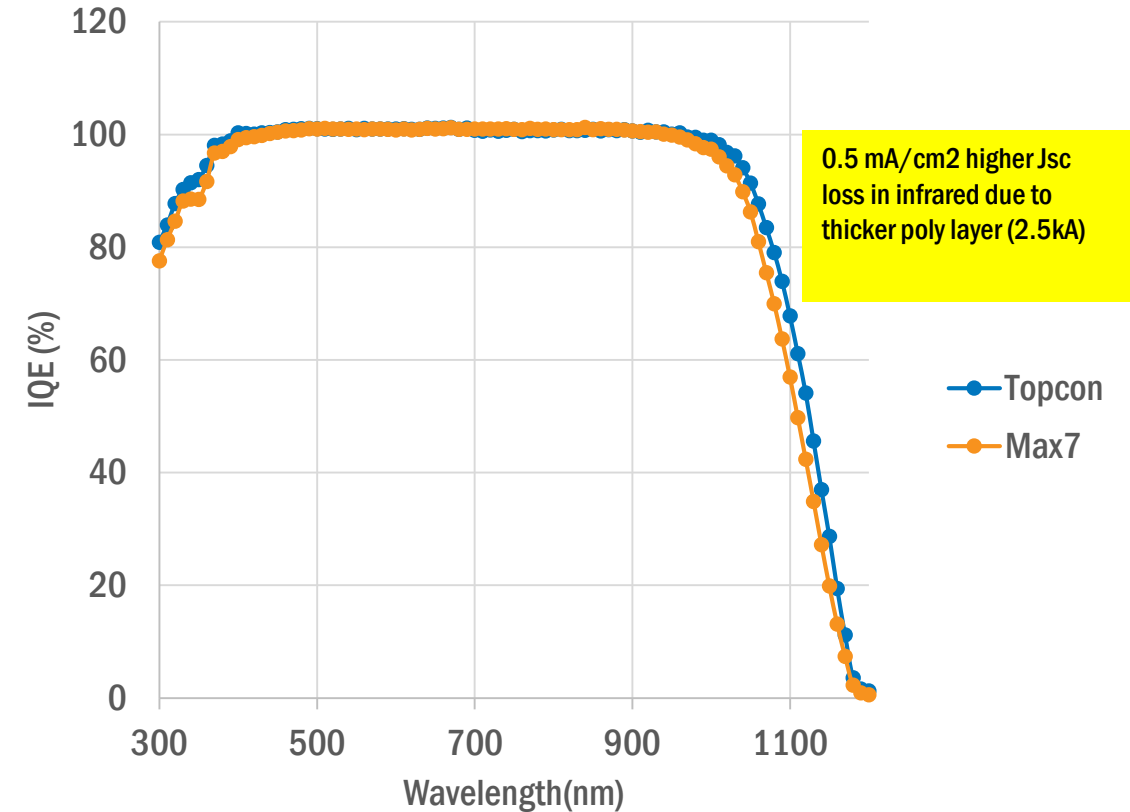
Aluminum wires metallization

- ❑ Maxeon 8 – Aluminum wire metallization system for cells, stringing, and matrix formation
- ❑ 25.3 % demonstrated, higher potential than copper, no solder pad dead space.
- ❑ Exceptional crack tolerance with high-strength wire continuously bonded to the cell
- ❑ Exceeds reliability tests for 40-year warranty
- ❑ Metal costs 30% of standard TOPCon systems, Aluminum \$3/kg, Silver \$1000/kg
- ❑ Developed in San Jose R&D lab, ongoing pilot line startup in Philippines



MY VISION OF MAXEON IBC ROADMAP

1. Zero volts reverse breakdown for best reliability and energy yield.
2. Improved free carrier absorption
 - Poly thickness currently well above Topcon at 2.5kA. Total available loss estimated at 0.5 %. Likely half accessible.
3. Advanced light trapping scheme.
 - Only thing that can enable >27 % cell and 26 % efficiency module.*



Thank you!